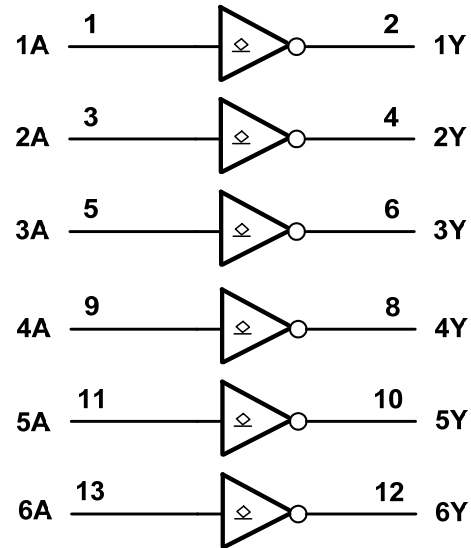


Pin Descriptions

Pin Number	Pin Name	Description
1	1A	Data Input
2	1Y	Data Output
3	2A	Data Input
4	2Y	Data Output
5	3A	Data Input
6	3Y	Data Output
7	GND	Ground
8	4Y	Data Output
9	4A	Data Input
10	5Y	Data Output
11	5A	Data Input
12	6Y	Data Output
13	6A	Data Input
14	Vcc	Supply Voltage

Logic Diagram



Function Table

Input	Output
A	Y
H	L
L	Z

Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to +7.0	V
V _I	Input Voltage Range (Note 4)	-0.5 to +7.0	V
I _{IK}	Input Clamp Current V _I < 0V	-20	mA
I _{OK}	Output Clamp Current V _O < 0V	-50	mA
I _O	Continuous Output Current - 0.5V < V _O < V _{CC} + 0.5V	- 25	mA
I _{CC}	Continuous Current Through Vcc	50	mA
I _{GND}	Continuous Current Through GND	-50	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
P _{TOT}	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 5) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage		2.0	5.5	V
V _I	Input Voltage		0	5.5	V
V _O	Output Voltage		0	5.5	V
I _{OL}	Low-Level Output Current	2.0V		50	μA
		2.3V to 2.7V		2	mA
		3.0V to 3.6V		6	mA
		4.5V to 5.5V		12	mA
Δt/ΔV	Input Transition Rise or Fall Rate	2.3V to 2.7V		200	ns/V
		3.0V to 3.6V		100	
		4.5V to 5.5V		20	
T _A	Operating Free-Air Temperature		-40	+125	°C

Note: 5. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V _{CC}	T _A = -40°C to +85°C		T _A = -40°C to +125°C		Unit
				Min	Max	Min	Max	
V _{IH}	High-Level Input Voltage		2.0V	1.5		1.5		V
			2.3V to 2.7V	V _{CC} X 0.7		V _{CC} X 0.7		
			3.0V to 3.6V	V _{CC} X 0.7		V _{CC} X 0.7		
			4.5V to 5.5V	V _{CC} X 0.7		V _{CC} X 0.7		
V _{IL}	Low-Level Input Voltage		2.0V		0.5		0.5	V
			2.3V to 2.7V		V _{CC} X 0.3		V _{CC} X 0.3	
			3.0V to 3.6V		V _{CC} X 0.3		V _{CC} X 0.3	
			4.5V to 5.5V		V _{CC} X 0.3		V _{CC} X 0.3	
V _{OL}	Low-Level Output Voltage	I _{OL} = 50μA	2.0V to 5.5V		0.1		0.1	V
		I _{OL} = 2mA	2.3V		0.4		0.4	
		I _{OL} = 6mA	3.0V		0.44		0.44	
		I _{OL} = 12mA	4.5V		0.55		0.55	
I _{OFF}	Power Down Leakage Current	V _I or V _O = 0 to 5.5V	0V		5		5	μA
I _I	Input Current	V _I = GND or 5.5V	0 to 5.5V		±1		±1	μA
I _{CC}	Supply Current	V _I = GND or V _{CC} I _O = 0	5.5V		20		20	μA

Switching Characteristics

 $V_{CC} = 2.5V \pm 0.2V$

Symbol	Parameter	Test Conditions	$T_A = +25^\circ C$			$-40^\circ C$ to $+85^\circ C$		$-40^\circ C$ to $+125^\circ C$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_{PLZ}	Propagation Delay A_N to Y_N	Figure 1 $C_L = 15pF$	—	3.6	10.4	1	13	1	13	ns
t_{PZL}			—	5.8	12.2	1	15	1	15	
t_{PLZ}		Figure 1 $C_L = 50pF$	—	6.1	15.2	1	18	1	18	ns
t_{PZL}			—	8.1	16.6	1	19.5	1	19.5	

 $V_{CC} = 3.3V \pm 0.3V$

Symbol	Parameter	Test Conditions	$T_A = +25^\circ C$			$-40^\circ C$ to $+85^\circ C$		$-40^\circ C$ to $+125^\circ C$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_{PLZ}	Propagation Delay A_N to Y_N	Figure 1 $C_L = 15pF$	—	2.9	7.1	1	8.5	1	8.5	ns
t_{PZL}			—	4	7.1	1	8.5	1	8.5	
t_{PLZ}		Figure 1 $C_L = 50pF$	—	4.7	10.6	1	12	1	12	ns
t_{PZL}			—	5.8	10.6	1	12	1	12	

 $V_{CC} = 5.0V \pm 0.5V$

Symbol	Parameter	Test Conditions	$T_A = +25^\circ C$			$-40^\circ C$ to $+85^\circ C$		$-40^\circ C$ to $+125^\circ C$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_{PLZ}	Propagation Delay A_N to Y_N	Figure 1 $C_L = 15pF$	—	2.2	5.5	1	6.5	1	6.5	ns
t_{PZL}			—	2.9	5.5	1	6.5	1	6.5	
t_{PLZ}		Figure 1 $C_L = 50pF$	—	3.4	7.5	1	8.5	1	8.5	ns
t_{PZL}			—	4.2	7.5	1	8.5	1	8.5	

Operating Characteristics

 $T_A = +25^\circ C$

Parameter		Test Conditions	V_{CC}	Typ	Unit
C_{pd}	Power Dissipation Capacitance per Gate	$f = 10MHz$	3.3V	2.5	pF
		$C_L = 50pF$	5.0V	3.0	

Noise Characteristics

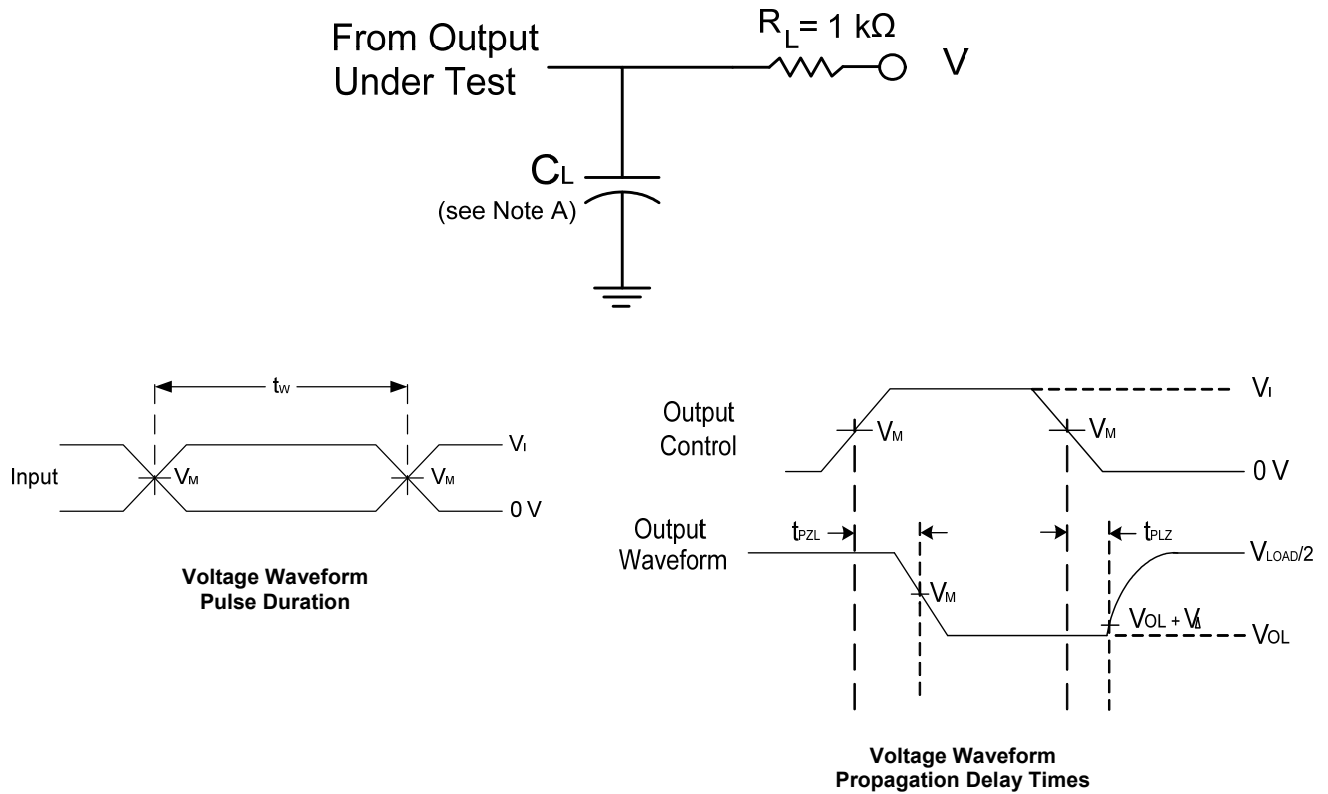
 $V_{CC} = 3V, C_L = 50pF, T_A = +25^\circ C$

Symbol	Parameter	Min	Typ	Max	Unit
$V_{OL(p)}$	Quiet output, maximum dynamic V_{OL}	—	0.2	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}	—	-0.1	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}	—	3.1	—	V
$V_{IH(D)}$	High Level dynamic input voltage	2.31	—	—	V
$V_{IL(D)}$	Low Level dynamic input voltage	—	—	0.99	V

Package Characteristics

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ	Max	Unit
C_i	Input Capacitance	$V_i = V_{CC} - \text{or GND}$	2.0V to 5.5V	—	3.3	10	pF

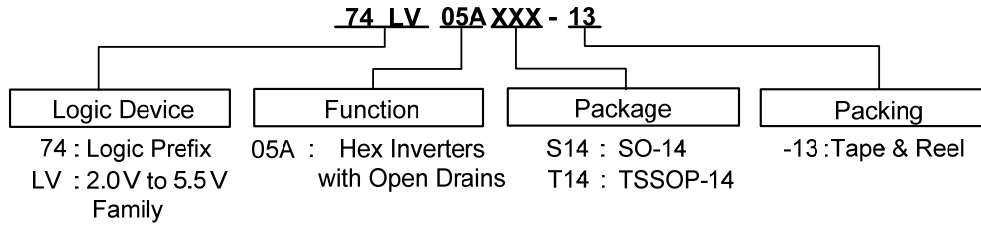
Parameter Measurement Information



- Notes: A. Includes test lead and test apparatus capacitance.
 B. All pulses are supplied at pulse repetition rate $\leq 10\text{ MHz}$
 D. For the open drain device t_{PLZ} and t_{PZL} are the same as t_{PD}
 E. t_{PZL} is measured at V_M .
 D. t_{PLZ} is measured at $V_{OL} + V_{\Delta}$ where $V_{\Delta} = 0.3\text{ V}$

Figure 1 Load Circuit and Voltage Waveforms

Ordering Information

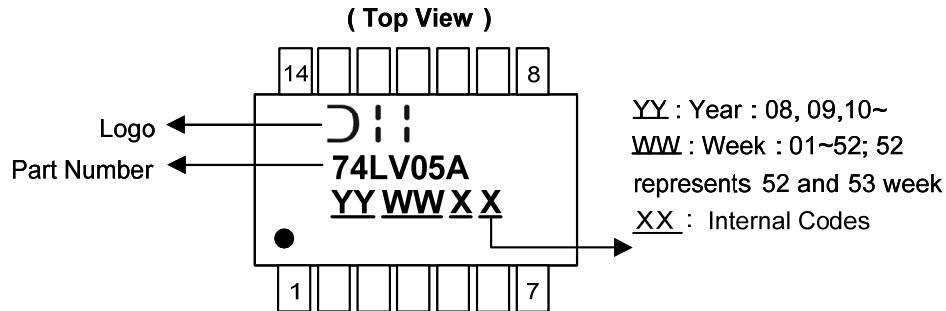


Part Number	Package Code	Packaging (Note 6)	13" Tape and Reel	
			Quantity	Part Number Suffix
74LV05AS14-13	S14	SO-14	2500/Tape & Reel	-13
74LV05AT14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Notes: 6. The taping orientation and tape details can be found at <http://www.diodes.com/datasheets/ap02007.pdf>

Marking Information

(1) SO14, TSSOP14

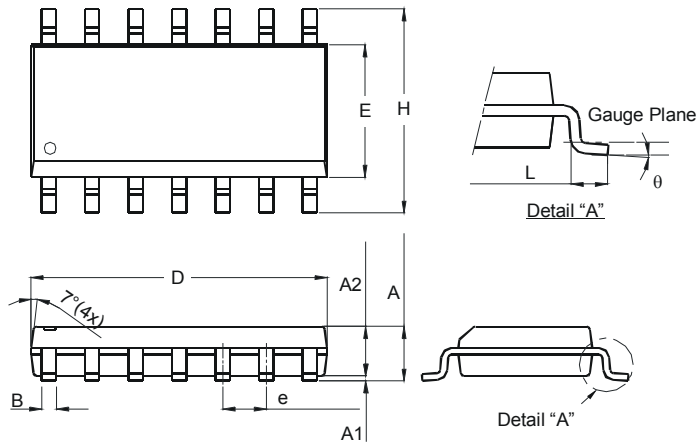


Part Number	Package
74LV05AS14	SO-14
74LV05AT14	TSSOP-14

Package Outline Dimensions (All dimensions in mm.)

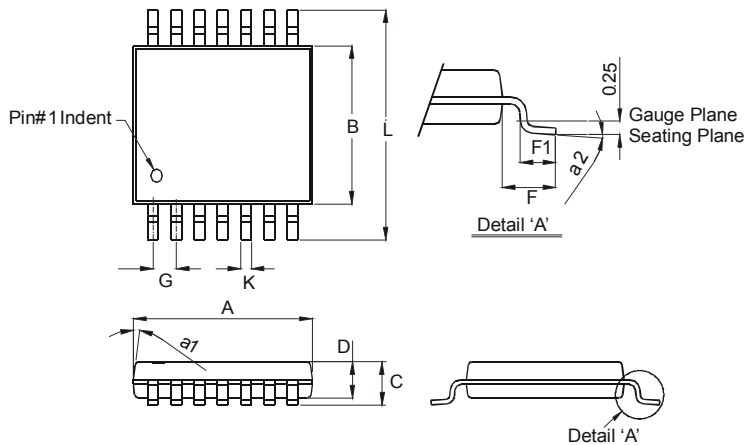
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

Package Type: SO-14



SO-14		
Dim	Min	Max
A	1.47	1.73
A1	0.10	0.25
A2	1.45 Typ	
B	0.33	0.51
D	8.53	8.74
E	3.80	3.99
e	1.27 Typ	
H	5.80	6.20
L	0.38	1.27
θ	0°	8°
All Dimensions in mm		

Package Type: TSSOP-14

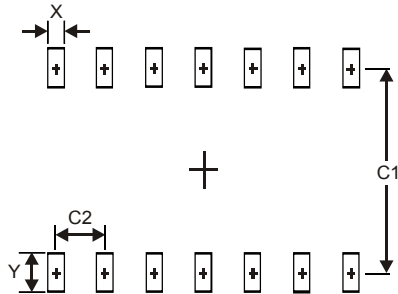


TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
A	4.9	5.10
B	4.30	4.50
C	—	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		

Suggested Pad Layout

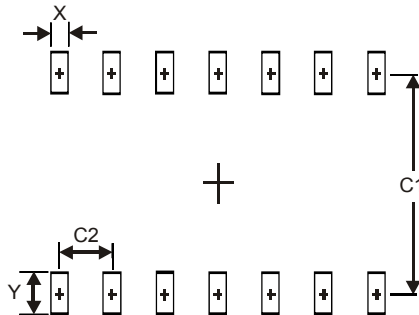
Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.

Package Type: SO-14



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

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